

General Description

The AP1682 is a high performance AC/DC universal input Primary Side Regulation Power Factor Controller for LED driver applications. The device uses Pulse Frequency Modulation (PFM) technology to regulate output current while achieving high power factor and low THD.

The AP1682 provides accurate constant current (CC) regulation while removing the opto-coupler and secondary control circuitry. It also eliminates the need of loop compensation circuitry while maintaining stability. The AP1682 achieves excellent regulation and high efficiency, yet meets the requirement of IEC61000-3-2 harmonic standard.

The AP1682 features low start-up current, low operation current and high efficiency. It also has rich protection features including over voltage, short circuit, over current, over temperature protection etc.

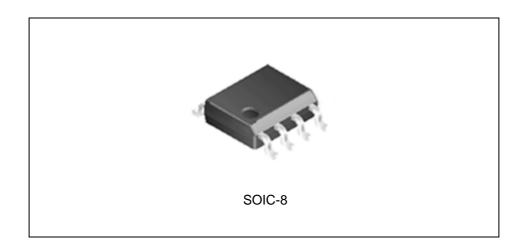
The AP1682 is available in SOIC-8 package.

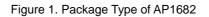
Features

- Primary Side Control for Output Current Regulation Without Opto-coupler and Secondary CV/CC Control Circuitry
- Low Start-up Current
- High Power Factor and Low THD for Universal Input Range
- Tight CC Regulation Performance for Universal Input Mains Voltage Range
- Eliminates Control Loop Compensation Circuitry
- Built-in Acceleration Start
- Open-load and Reload Detection
- Over Voltage and Short Circuit Protection
- Over Temperature Protection
- Over Current Protection
- Cost Effective Total PFC LED Driver Solution

Applications

• Single Stage Power Factor Correction Power Supply for LED Lighting

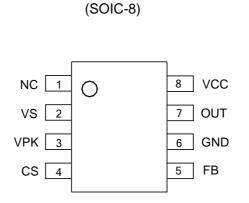






M Package

Pin Configuration





Pin Description

| Pin Number | Pin Name | Function |
|------------|----------|---|
| 1 | NC | No connection |
| 2 | VS | The rectified input voltage sensing pin. The pin is detecting the instantaneous rectified sine waveform of input voltage |
| 3 | VPK | The rectified input voltage peak value sensing pin. The pin is detecting the rectified sine waveform peak value of input voltage |
| 4 | CS | Primary current sensing |
| 5 | FB | This pin captures the feedback voltage from the auxiliary winding. FB voltage is used to control no load output voltage and determine acceleration stop point at start-up phase |
| 6 | GND | Ground. Current return for gate driver and control circuits of the IC |
| 7 | OUT | Gate driver output |
| 8 | VCC | Supply voltage of gate driver and control circuits of the IC |



AP1682

Functional Block Diagram

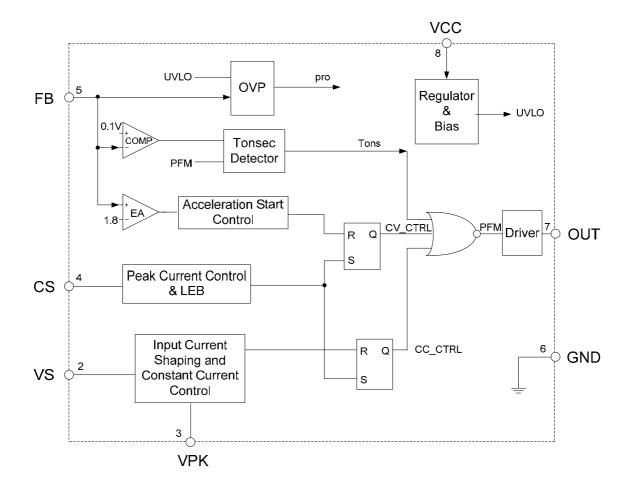
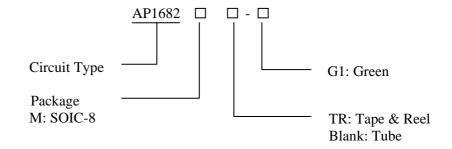


Figure 3. Functional Block Diagram of AP1682



Ordering Information



| Package | Temperature Range | Part Number | Marking ID | Packing Type | |
|---------|----------------------|--------------|------------|--------------|--|
| SOIC-8 | -40 to 105°C | AP1682M-G1 | 1682M-G1 | Tube | |
| | | AP1682MTR-G1 | 1682M-G1 | Tape & Reel | |

BCD Semiconductor's Pb-free products, as designated with "G1" suffix in the part number, are RoHS compliant and green.



AP1682

Absolute Maximum Ratings (Note 1)

| Parameter | Symbol | Value | Unit | |
|---|---|------------|------|--|
| Power Supply Voltage | V _{CC} | -0.3 to 30 | V | |
| Driver Output Current | I _{OUT} | 300 | mA | |
| Voltage at VS, VPK, CS | V _{VS} , V _{PK} , V _{CS} | -0.3 to 7 | V | |
| FB Input Voltage | V _{FB} | -40 to 10 | V | |
| Operating Junction Temperature | T _J | 150 | °C | |
| Storage Temperature | T _{STG} | -65 to 150 | °C | |
| Lead Temperature (Soldering, 10 sec) | T _{LEAD} | 300 | °C | |
| Power Dissipation at T _A =50°C | P _D | 0.65 | W | |
| Thermal Resistance (Junction-to-Ambient) | θ_{JA} | 190 | °C/W | |
| ESD (Machine Model) | | 200 | V | |
| ESD (Human Body Model) | | 3000 | V | |

Note 1: Stresses greater than those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "Recommended Operating Conditions" is not implied. Exposure to "Absolute Maximum Ratings" for extended periods may affect device reliability.

Recommended Operating Conditions

| Parameter | Symbol | Min | Max | Unit | |
|----------------------|-----------------|-----|-----|------|--|
| Power Supply Voltage | V _{CC} | 9 | 21 | V | |
| Ambient Temperature | T _A | -40 | 105 | °C | |



AP1682

Electrical Characteristics

| Parameter | Symbol | Conditions | Min | Тур | Max | Unit | |
|-------------------------------------|--|--|-----|------|------|------|--|
| UVLO Section | | | | | | | |
| Start-up Threshold | V _{TH} (ST) | | 18 | 19 | 20 | | |
| Minimal Operating Voltage | V _{OPR} (Min) | After turn on | 7 | 8 | 9 | V | |
| VCC OVP Voltage | V _{CC_OVP} | | 28 | 32 | 36 | | |
| Standby Current Section | | | | | | | |
| Start-up Current | I _{ST} | $V_{CC} = V_{TH} (ST) - 0.5V,$ Before start up | | | 20 | | |
| Maximum Operating Current | I _{CC} (Max) | V _{VS} =V _{PK} =3V | | 1000 | 1300 | μA | |
| Drive Output Section | | | | | | | |
| Output High Level Voltage | V _{OH} | I _{GD-SOURCE} =20mA V _{CC} =12V | 10 | | | V | |
| Output Low Level Voltage | V _{OL} | I _{GD-SINK} =20mA V _{CC} =12V | | | 1 | V | |
| Output Voltage Rise Time | t _R | C _L =1nF | 100 | 140 | 190 | ns | |
| Output Voltage Fall Time | t _F | C _L =1nF | 30 | 60 | 90 | ns | |
| Output Clamp Voltage | V _{O-CLAMP} | $I_{GD-SOURCE}=5mA$ $V_{CC}=20V$ | 12 | 13.5 | 15 | V | |
| UVLO Saturation Voltage | V _{UVLO} | $V_{CC}=0$ to V_{CC-ON} $I_{SINK}=10mA$ | | | 1.1 | V | |
| VS Input Section | | | | | | | |
| Maximum Ratio | V _{VS} /V _{PK} (Max) | V _{VS} =V _{PK} =3V | 0.8 | 1 | 1.2 | V | |
| Minimum Ratio | V _{VS} /V _{PK} (Min) | $V_{VS}=0V, V_{PK}=3V$ | | | 0.2 | V | |
| Current Sense Section | | | | | | | |
| Minimum On Time | t _{ON} (Min) | | 500 | 750 | 1000 | ns | |
| Short Circuit Protection Voltage | V _{SOCP} | | 3 | 4 | | V | |
| Feedback Input Section | | | | | | | |
| FB Pin Input Leakage Current | I _{FB} | V _{FB} =4V | | 2 | 8 | μΑ | |
| Acceleration Start Threshold | V _{FB} (ACC) | | 1.4 | 1.8 | 2.2 | V | |
| CV Threshold | $V_{FB}(CV)$ | | 3.2 | 4.2 | 5.2 | V | |
| Over Voltage Protection | V _{FB} (OVP) | | 4.5 | 6 | 7.5 | V | |
| Over Temperature Protection Section | | | | | | | |
| Shutdown Temperature | | | | 140 | | °C | |
| Temperature Hysteresis | | | | 20 | | °C | |

 $V_{CC}\!=\!\!15V\!, T_{A}\!=\!\!25^{\circ}C\!,$ unless otherwise specified.

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AP1682

Typical Performance Characteristics

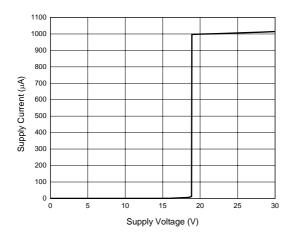


Figure 4. Supply Current vs. Supply Voltage

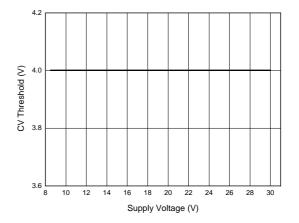


Figure 5. CV Threshold Vs. Supply Voltage

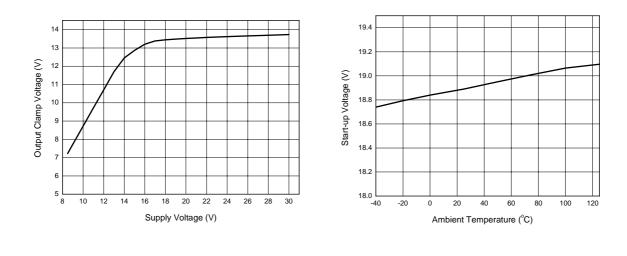
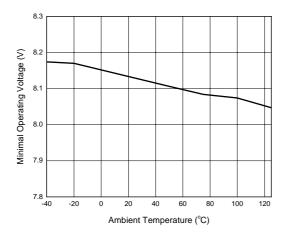


Figure 6. Output Clamp Voltage vs. Supply Voltage Figure 7. Start-up Voltage vs. Ambient Temperature



Typical Performance Characteristics (Continued)



8.0 7.5 7.0 6.5 Start-up Current (µA) 6.0 5.5 5.0 4.5 4.0 3.5 3.0 2.5 2.0 └─ -40 -20 0 20 40 60 80 100 120 Ambient Temperature (°C)

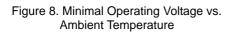


Figure 9. Start-up Current vs. Ambient Temperature

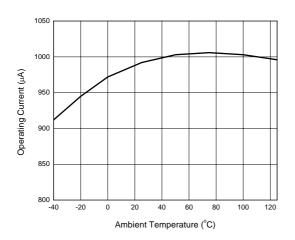


Figure 10. Operating Current vs. Ambient Temperature

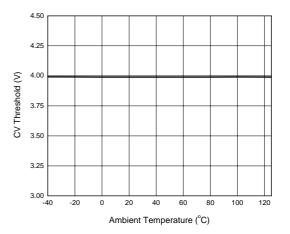


Figure 11. CV Threshold Vs. Ambient Temperature

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Typical Performance Characteristics (Continued)

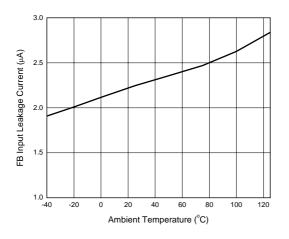


Figure 12. FB Input Leakage Current vs. Ambient Temperature

Typical Application

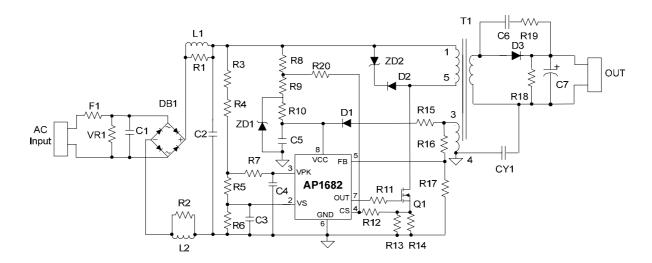


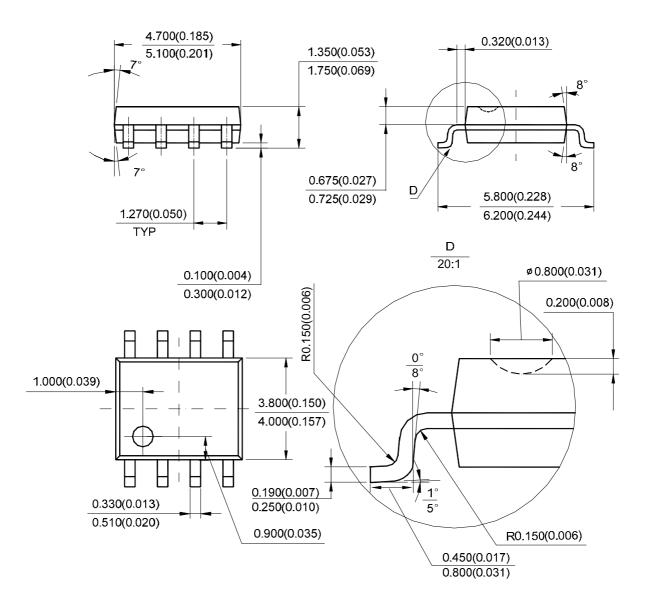
Figure 13. Typical Application of AP1682



Mechanical Dimensions

Unit: mm(inch)





Note: Eject hole, oriented hole and mold mark is optional.



BCD Semiconductor Manufacturing Limited

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